

EAST - [10800630.wsp:1]

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Default operator: OR Highlight all hit terms initially

packag\$3 and (protecting near cover protecting near cap) and semiconductor

Drafts

Pending

Active

L1: (48) semiconductor and packag\$3 and protection near cover

L2: (5) semiconductor and protection near cover and (chip near size near package multi near

L3: (7) protection near cover and (chip near size near package multi near chip near package)

L4: (53) (protection with cover) and (chip near size near package multi near chip near package)

L5: (1) (cover with project\$3) and (chip near size near package multi near chip near package)

L6: (24) (cover with project\$3) and (chip near size near package multi near chip near package)

L7: (73) (IC near cover) and (suction)

L8: (1) (IC near cover) and probe near pin

L9: (37) (IC near cover cover with protect\$3) and probe near pin

L10: (133) (IC near cover cover) and probe near pin and semiconductor

L11: (212708) packag\$3 and (protecting near cover cover cap)

L12: (64121) packag\$3 and (protecting near cover cap)

L13: (620) packag\$3 and (protecting near cover protecting near cap)

L14: (79) packag\$3 and (protecting near cover protecting near cap) and semiconductor

Failed

*protection with cover) and (chip near size near package multi near chip near package)

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	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
39	<input type="checkbox"/>	<input type="checkbox"/>	US 6346742 B1	20020212	15	Chip-scale packaged pressure sensor	257/704	257/419; 257/619
40	<input type="checkbox"/>	<input type="checkbox"/>	US 6331111 B1	20011218	30	Curing light system useful for curing light activated composite materials	433/29	362/119; 362/800; 362/804
41	<input type="checkbox"/>	<input type="checkbox"/>	US 6313529 B1	20011106	19	Bump bonding and sealing a semiconductor device with solder	257/724	257/778; 257/780; 257/E21.511
42	<input type="checkbox"/>	<input type="checkbox"/>	US 6257701 B1	20010710	33	Ink jet recording apparatus having an exchangeable ink jet head cartridge mountable thereon and recovery method of said cartridge	347/49	347/5
43	<input type="checkbox"/>	<input type="checkbox"/>	US 6255741 B1	20010703	20	Semiconductor device with a protective sheet to affix a semiconductor chip	257/792	257/414; 257/467; 257/468
44	<input type="checkbox"/>	<input type="checkbox"/>	US 6250827 B1	20010626	58	Recording device and sheet material conveying device	400/691	400/88
45	<input type="checkbox"/>	<input type="checkbox"/>	US 6219484 B1	20010417	8	Metal coated optical fiber array module	385/137	385/65; 385/83
46	<input type="checkbox"/>	<input type="checkbox"/>	US 6190020 B1	20010220	16	Light producing assembly for a flashlight	362/184	362/205; 362/800
47	<input type="checkbox"/>	<input type="checkbox"/>	US 6146918 A	20001114	12	Method of fabricating a semiconductor package	438/106	257/666; 257/678; 257/E23.004
48	<input type="checkbox"/>	<input type="checkbox"/>	US 6057597 A	20000502	9	Semiconductor package with pre-fabricated cover	257/710	257/698; 257/704; 257/723
49	<input type="checkbox"/>	<input type="checkbox"/>	US 6054818 A	20000425	78	Electric motor vehicle	318/139	363/55

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